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TABLE OF CONTENTS

QUANTUM COMPUTING AND THE IMPORTANCE OF INTERCONNECTS	1
<i>J. S. Clarke</i>	
THE FUTURE OF INTERCONNECTS: CHALLENGES AND ENABLING TECHNOLOGIES (INVITED)	2
<i>K. Lin, M. Chandhok, M. Reshotko</i>	
HIGH-ASPECT-RATIO RUTHENIUM LINES FOR BURIED POWER RAIL.....	4
<i>A. Gupta, S. Kundu, L. Teugels, J. Bömmels, C. Adelman, N. Heylen, G. Jamieson, O. V. Pedreira, I. Ciofi, B. Chava, C. J. Wilson, Z. Tókei</i>	
ELECTROLESS COBALT VIA PRE-FILL PROCESS FOR ADVANCED BEOL METALLIZATION AND VIA RESISTANCE VARIATION REDUCTION.....	7
<i>J. Gu, D. Zhao, M. Kamon, D. M. Fried, G. Harm, T. Mountsier</i>	
SUBTRACTIVE ETCH OF RUTHENIUM FOR SUB-5NM INTERCONNECT.....	10
<i>D. Wan, S. Paolillo, N. Rassoul, B. K. Kotowska, V. Blanco, C. Adelman, F. Lazzarino, M. Ercken, G. Murdoch, J. Bömmels, C. J. Wilson, Z. Tókei</i>	
IMPACT OF LINER METALS ON COPPER RESISTIVITY AT BEYOND 7NM DIMENSIONS	13
<i>H. Huang, N. Lanzillo, T. E. Standaert, K. Motoyama, C. Yang, H. Shobha, J. F. Maniscalco, T. Nogami, J. Li, T. A. Spooner, G. Bonilla</i>	
CHALLENGES AND PROGRESS ON CARBON NANOTUBE INTEGRATION FOR BEOL INTERCONNECTS (INVITED).....	16
<i>B. Uhlig, A. Dhavamani, N. Nagy, K. Lilienthal, R. Liske, R. Ramos, J. Dijon, H. Okuno, D. Kalita, J. Lee, V. Georgiev, A. Asenov, S. Amoroso, L. Wang, F. Koenemann, B. Gotsmann, G. Goncalves, B. Chen, J. Liang, R. R. Pandey, R. Chen, A. Todri-Sanial</i>	
CMOS-COMPATIBLE CONTACTS FOR SI PHOTONICS FROM SOLID-STATE REACTION TO LASER INTEGRATION	19
<i>E. Ghegin, S. Zhiou, S. Bensalem, L. Toselli, M. Pasquali, S. Favier, C. Jany, B. Szlag, P. Gergaud, F. Nemouchi, P. Rodriguez</i>	
SINGLE CRYSTAL AL INTERCONNECTS FORMED ON P-GAN AND THEIR APPLICATION TO GAN FET.....	22
<i>T. Harada, K. Utaka, Y. Kanda, K. Onishi, K. Matsunaga, M. Hikita, Y. Uemoto</i>	
GRAPHENE INTERCONNECTS - HIGH PERFORMANCE TWISTED 20 NM GRAPHENE RIBBONS	25
<i>Xiangyu Wu, I. Asselberghs, C. Huyghebaert, A. Contino, B. Soree, M. Heyns, Zsolt Tokei</i>	
CONTACT METALLIZATION FOR ADVANCED CMOS TECHNOLOGY NODES (INVITED)	28
<i>V. Kamineni, A. Carr, C. Niu, P. Adusumilli, T. Abrams, R. Xie, S. Fan, J. Kelly, H. Amanapu, S. Tsai, K. Ryan, Y. Liang, X. Lin, S. Choi, H. Dixit, A. Konar, N. Lanzillo, H. Wu, J. Cho, D. Guo, K. Choi, M. V. Raymond</i>	
EXTREME CONTACT SCALING WITH ADVANCED METALLIZATION OF COBALT	30
<i>R. Hung, Jin H. Park, Tae H. Ha, Mark Lee, Wenting Hou, Jianxin Lei, J. R. Bakke, S. Sharma, K. R. Sharma, A. Wachs, Nam S. Kim, E. Yeh</i>	
REPLACEMENT METAL CONTACT USING SACRIFICIAL ILD0 FOR WRAP AROUND CONTACT IN SCALED FINFET TECHNOLOGY.....	33
<i>S.-A. Chew, S. Demuyne, L. Zhang, A. Pocco, K. Devriendt, L. Teugels, T. Hopf, J. Versluijs, C. Vrancken, A. Dangol, E. Altamirano Sanchez, D. Mocuta, N. Horiguchi</i>	
VALIDITY AND APPLICATION OF THE TCR METHOD TO MOL CONTACTS.....	36
<i>E. Milosevic, V. Kamineni, X. Zhang, H. Dixit, M. V. Raymond, H. Huang, R. Southwick, C. Janicki, N. Lanzillo</i>	
CMOS/CU BEOL TECHNOLOGY IN MANUFACTURING: 20 YEARS AND COUNTING	39
<i>D. Edelstein</i>	
RU LINER SCALING WITH ALD TAN BARRIER PROCESS FOR LOW RESISTANCE 7 NM CU INTERCONNECTS AND BEYOND	40
<i>K. Motoyama, O. van der Straten, J. Maniscalco, H. Huang, Y. Kim, J. K. Choi, J. H. Lee, C.-K. Hu, P. McLaughlin, T. Standaert, R. Quon, G. Bonilla</i>	
MODIFIED ALD TAN BARRIER WITH RU LINER AND DYNAMIC CU REFLOW FOR 36NM PITCH INTERCONNECT INTEGRATION.....	43
<i>P. S. Bhosale, J. Maniscalco, N. Lanzillo, T. Nogami, D. Canaperi, K. Motoyama, H. Huang, P. McLaughlin, R. Shaviv, M. Stolfi, R. Vinnakota, G. How, S. Pethe, B. Sheu, X. Xie, L. Chen</i>	
MICROSTRUCTURE EVOLUTION AND IMPLICATIONS FOR CU NANOINTERCONNECTS AND BEYOND	46
<i>Szu-Tung Hu, Linjun Cao, L. Spinella, Paul S. Ho</i>	

ELECTROMIGRATION AND THERMAL STORAGE STUDY OF BARRIERLESS CO VIAS	48
<i>O. V. Pedreira, K. Croes, H. Zahedmanesh, K. Vandersmissen, M. H. van der Veen, V. V. Gonzalez, D. Dictus, L. Zhao, A. Kolics, Z. Tőkei</i>	
PATHFINDING OF RU-LINER/CU-REFLOW INTERCONNECT RELIABILITY SOLUTION.....	51
<i>Zhiyuan Wu, Feng Chen, Gang Shen, Yufei Hu, S. Pethe, Joung J. Lee, J. Tseng, W. Suen, R. Vinnakota, K. Kashefzadeh, M. Naik</i>	
TESTING THE LIMITS OF TAN BARRIER SCALING.....	54
<i>C. Witt, K. B. Yeap, A. Leśniewska, D. Wan, N. Jordan, I. Ciofi, C. Wu, Z. Tőkei</i>	
SURFACE FUNCTIONALIZATION FOR CONDUCTIVITY IMPROVEMENT BY METAL ATOMIC LAYER DEPOSITION (INVITED)	57
<i>H.-B.-R. Lee</i>	
NONAFFINE DEFORMATIONS IN ULK DIELECTRIC GLASSES	58
<i>K. I. Kilic, R. H. Dauskardt</i>	
EFFECT OF THERMAL ANNEALING ON LOW-K DIELECTRICS FOR IBEOL IN VIEW OF 3D SEQUENTIAL INTEGRATION	61
<i>S. Beaupaire, V. Jousseau, P. Gonon, A. Bsiesy, C. Guérin, N. Rochat, C. Licitra, P.-L. Charvet, M. Veillerot, N. Rambal, D. Nouguier, D. Ney, X. Federspiel, C. Fenouillet-Béranger</i>	
BEOL LAYOUT DESIGN CONSIDERATIONS TO MITIGATE CPI RISK	64
<i>M. A. Rabie, T. Raman, F. Mirza, N. A. Polomoff, D. Faruqi, S. Pozder, M. K. Hassan, T. Desouky, C. Graas</i>	
SYSTEM-LEVEL IMPACT OF INTERCONNECT LINE-EDGE ROUGHNESS	67
<i>R. Baert, I. Ciofi, P. Roussel, L. Mattii, P. Debacker, Z. Tokei</i>	
IMPACT OF LINE AND VIA RESISTANCE ON DEVICE PERFORMANCE AT THE 5NM GATE ALL AROUND NODE AND BEYOND.....	70
<i>N. A. Lanzillo, K. Motoyama, T. Hook, L. Clevenger</i>	
INTERCONNECT-DEVICE CO-OPTIMIZATION FOR FIELD-EFFECT TRANSISTORS WITH TWO-DIMENSIONAL MATERIALS	73
<i>D. Verreck, G. Arutchelvan, I. Ciofi, M. M. Heyns, I. P. Radu</i>	
TUNGSTEN PLUG MISSING DEFECTS MONITORING METHOD AND ITS SOLUTION BY OPTIMIZATION OF POLYMER CLEANING AND MICRO-ENVIRONMENT	76
<i>R. Fan, Hunglin Chen, Kai Wang, Yin Long, Qiliang Ni</i>	
SILICON TRENCH ETCH UNIFORMITY IMPROVEMENT FOR MICROLOADING AND MACRO-TO-MACRO LOADING FOR SUB-14NM NODE.....	79
<i>Yong M. Yang, Sang W. Lim, Junsic Hong, M. Park, Yinxiao Yang, Wang K. Cho, C. Adams, M. Aminpur, Chang H. Maeng</i>	
MODULATION OF WITHIN-WAFER AND WITHIN-DIE TOPOGRAPHY FOR DAMASCENE COPPER IN ADVANCED TECHNOLOGY	82
<i>W.-T. Tseng, T.-J. Cheng, S. Ahmed, Jusang Lee, F. Baumann</i>	
THE IMPACT OF SOLUTE SEGREGATION ON GRAIN BOUNDARIES IN DILUTE CU ALLOYS.....	85
<i>T. Tsurumaru, L. Prestowitz, B. O'Brien, K. Dunn</i>	
MODELING WAFER BENDING EFFECTS ON RDL LAYER RELIABILITY IN A MULTIPLE DIE PACKAGE	88
<i>Tzu C. Wang, Chih C. Yeh, Xiaopeng Xu, K. El Sayed, Chun-Hung S. Lin</i>	
SILICIDE BASED LOW TEMPERATURE AND LOW PRESSURE BONDING OF TI/SI FOR MICROFLUIDICS AND HERMETIC SEALING APPLICATION	91
<i>C. H. Kumar, A. K. Pnagrahi, N. Paul, S. Bonam, S. R. K. Vanjari, S. G. Singh, A. K. Panigrahi</i>	
A HIGHLY RELIABLE 1X5UM VIA-LAST TSV MODULE.....	94
<i>S. Van Huylbroeck, Yunlong Li, J. De Vos, G. Jamieson, N. Tutunjan, A. Miller, G. Beyer, E. Beyne</i>	
STRATEGY OF INSERTION OF MERGE FEATURES IN A SEA OF WIRES SADP INTEGRATION	97
<i>James H.-C. Chen, T. A. Spooner, L. A. Clevenger, M. O'Toole, A. Ogino, L. Lanzerotti, S. Reidy, C. Child</i>	
A STUDY ON SADP PROCESS REFRESH FOR PATTERNING CORRECTION.....	100
<i>James H.-C. Chen, I. C. Estrada-Raygoza, C. B. Peethala, Y. Mignot, H. Shobha, T. E. Standaert</i>	
IMPACT OF SN CONTENT IN GE_{1-X}SN_X LAYERS ON NI STANOGERMANIDES SOLID-STATE REACTION AND PROPERTIES	103
<i>A. Quintero, P. Gergaud, N. Chevalier, J. Aubin, J. M. Hartmann, V. Loup, V. Reboud, E. Cassan, P. Rodriguez</i>	
EFFECTIVE METHODS CONTROLLING CU OVERBURDENS FOR CU RDL PROCESS.....	106
<i>Kimoon Park, Jinhyun Lee, Bongyoung Yoo</i>	
PHYSICAL AND ELECTRICAL PROPERTIES OF NEW ZR PRECURSORS WITH HIGH THERMAL STABILITY FOR HIGH-K	109
<i>H.-D. Lim, Sang-Yong Jeon, Won-Mook Chae, Joong-Jin Park, Sang-Jun Yim, Sang-Ick Lee, Myong-Woon Kim</i>	

OXIDATION STRUCTURE CHANGE OF COPPER SURFACE DEPENDING ON ACCELERATED HUMIDITY	112
<i>P. Gomasang, S. Ogiue, K. Ueno, S. Yokogawa</i>	
NON-REAGENT EXPRESS METROLOGY FOR MODERN DAMASCENE COPPER PLATING BATHS	115
<i>M. Pavlov, Danni Lin</i>	
STRESS INDUCED DENSIFICATION OF THIN POROUS LOW-K FILMS DURING NANOINDENTATION	118
<i>O. O. Okudur, M. Redzheb, K. Vanstreels, H. Zahednamesh, M. Gonzalez, I. De Wolf</i>	
INTEGRATION OF METALLIZATION PROCESSES IN ROBUST INTERCONNECTS FORMATION FOR 14 NM NODES AND BEYOND	121
<i>N. Petrov, S. B. Law, J. Rullan, Seungman Choi, S. L. Liew, Han W. Ng, S. Kakita</i>	
ELECTROLYTIC COBALT FILL OF SUB-5 NM NODE INTERCONNECT FEATURES	123
<i>F. Wafula, J. Wu, S. Branagan, H. Suzuki, A. Gracias, J. van Eysden</i>	
AN INNOVATIVE SYSTEM INTEGRATION INTERCONNECTION TECHNOLOGY BEYOND BEOL	126
<i>Dyi-Chung Hu</i>	
GAS PHASE PORE STUFFING (GPPS): A NEW METHOD TO PROTECT POROUS LOW-K MATERIALS	129
<i>M. Fujikawa, T. Yamaguchi, S. Nozawa, R. Niino, R. Chanson, K. B. Gavan, F. Lazzarino, J.-F. de Marneffe</i>	
CU BARRIER PROPERTIES OF CLUSTER-PREFORMING-DEPOSITED AMORPHOUS WSi_N FILMS DEPENDING ON COMPOSITION N	132
<i>N. Okada, N. Uchida, S. Ogawa, T. Kanayama</i>	
CHARGE-TRAP-FREE POLYMER-LINER THROUGH-SILICON VIAS FOR RELIABILITY IMPROVEMENT OF 3D ICS	135
<i>H. Kino, Sungho Lee, Y. Sugawara, T. Fukushima, T. Tanaka</i>	
SPRAY PLASMA PROCESSING OF BARRIER FILMS DEPOSITED IN AIR FOR IMPROVED STABILITY OF FLEXIBLE ELECTRONIC DEVICES	138
<i>N. Rolston, A. D. Printz, F. Hilt, M. Q. Hovish, K. Brüning, C. J. Tassone, R. H. Dauskardt</i>	
ADVANCED METALLIZATION PROCESSES INTEGRATION AS MANUFACTURING WORTHY SOLUTIONS FOR >10:1 ASPECT RATIO MID-PROCESS TSV	141
<i>T. Mourier, M. Gottardi, C. Ribière, G. Romero, S. Minoret, P.-E. Philip</i>	
INTERCONNECT STACK USING SELF-ALIGNED QUAD AND DOUBLE PATTERNING FOR 10NM HIGH VOLUME MANUFACTURING (INVITED)	144
<i>A. Yeoh, A. Madhavan, N. Kybert, S. Anand, J. Shin, M. Asoro, S. Samarajeewa, J. Steigerwald, C. Ganpule, M. Buehler, A. Tripathi, V. Souw, M. Haran, S. Nigam, V. Chikarmane, P. Yashar, T. Mulé, Y.-H. Wu, K.-S. Lee, M. Aykol, K. Marla, P. Sinha, S. Kirby, H. Hiramatsu, W. Han, M. Mori, M. Sharma, H. Jeedigunta, M. Sprinkle, C. Pelto, M. Tanniru, G. Leatherman, K. Fischer, I. Post, C. Auth</i>	
PROCESS CHALLENGES IN FULLY ALIGNED VIA INTEGRATION FOR SUB 32 NM PITCH BEOL (INVITED)	148
<i>B. D. Briggs, C. B. Peethala, D. L. Rath, J. Lee, S. Nguyen, N. V. LiCausi, P. S. McLaughlin, H. You, D. Sil, N. A. Lanzillo, H. Huang, R. Patlolla, T. Haigh, Y. Xu, C. Park, P. Kerber, H. K. Shobha, Y. Kim, J. Demarest, J. Li, G. Lian, M. Ali, C. Le, E. T. Ryan, L. A. Clevenger, D. F. Canaperi, T. E. Standaert, G. Bonilla, E. Huang</i>	
PVD-TREATED ALD TAN FOR CU INTERCONNECT EXTENSION TO 5NM NODE AND BEYOND	149
<i>Zhiyuan Wu, Rui Li, Xiangjin Xie, W. Suen, J. Tseng, N. Bekiaris, R. Vinnakota, K. Kashefzadeh, M. Naik</i>	
INTERCONNECT CHALLENGES AND OPPORTUNITIES IN THE MEMORY SPACE (INVITED)	152
<i>J. Smythe, M. Milojevic, G. Herdt, S. Pandey, R. Hill</i>	
ALTERNATIVE METALS: FROM AB INITIO SCREENING TO CALIBRATED NARROW LINE MODELS (INVITED)	154
<i>C. Adelman, K. Sankaran, S. Dutta, A. Gupta, S. Kundu, G. Jamieson, K. Moors, N. Pinna, I. Ciofi, S. Van Elshocht, J. Bömmels, G. Boccardi, C. J. Wilson, G. Pourtois, Z. Tókei</i>	
METALS FOR LOW-RESISTIVITY INTERCONNECTS	157
<i>D. Gall</i>	
METALLIC CERAMICS FOR LOW RESITIVITY INTERCONNECTS: AN AB INITIO INSIGHT	160
<i>K. Sankaran, K. Moors, S. Dutta, C. Adelman, Z. Tókei, G. Pourtois</i>	
A FIRST-PRINCIPLES DENSITY FUNCTIONAL THEORY BASED FRAMEWORK FOR BARRIER MATERIAL SCREENING	163
<i>G. Hegde, C. R. Bowen, H. Simka</i>	

RESISTANCE SCALING OF CU INTERCONNECT AND ALTERNATE METAL (CO, RU)	
BENCHMARK TOWARD SUB 10NM DIMENSION.....	166
<i>He Ren, Zhiyuan Wu, N. Bekiaris, J. Tseng, G. How, Xiangjin Xie, Wei Lei, Rong Tao, R. Shaviv, Joung J. Lee, R. Vinnakota, K. Kashefzadeh, M. Gage, M. Naik</i>	
EMBEDDED METAL VOIDS DETECTION TO IMPROVE COPPER METALLIZATION FOR	
ADVANCED INTERCONNECT	169
<i>J. Tseng, M. Naik, A. Kumar, K. Nafisi, Joung J. Lee, Zhiyuan Wu, K. Moraes, A. Wachs, D. Shemesh, J. Fernandez</i>	
DAMASCENE BENCHMARK OF RU, CO AND CU IN SCALED DIMENSIONS.....	172
<i>M. H. van der Veen, N. Heylen, O. V. Pedreira, I. Ciofi, S. Decoster, V. V. Gonzalez, N. Jourdan, H. Struyf, K. Croes, C. J. Wilson, Z. Tôkei</i>	
FROM DIRECT BONDING MECHANISM TO 3D APPLICATIONS (INVITED)	175
<i>F. Fournel, H. Moriceau, V. Larrey, C. Morales, C. Mauguen, C. Bridoux, F. Rieutord</i>	
ADVANCES IN SICN-SICN BONDING WITH HIGH ACCURACY WAFER-TO-WAFER (W2W)	
STACKING TECHNOLOGY	179
<i>L. Peng, S.-W. Kim, S. Iacovo, F. Inoue, A. Phommahaxay, E. Sleenckx, J. De Vos, D. Zinner, T. Wagenleitner, T. Uhrmann, M. Wimplinger, B. Schoenaers, A. Stesmans, V. V. Afanas'ev, A. Miller, G. Beyer, E. Beyne</i>	
NOVEL BONDING PROCESS USING ULTRA-THIN MN FOR HIGHLY ROBUST AND	
RELIABLE CU/SIO HYBRID BONDING	182
<i>K. Uchida, K. Tsumura, K. Nakamura, K. Higashi, Y. Sugizaki, H. Shibata</i>	
BEAT THE HEAT IN 3D CHIP STACKS WITH NOVEL MICROFLUIDICS (INVITED)	185
<i>T. Chainer, P. R. Parida, M. Schultz, F. Yang, M. Gaynes, G. McVicker, A. Sridhar, S. Paredes, O. Ozsun, T. Brunschwiler, U. Drechsler, E. Colgan, B. Dang, Y. Liu, Q. Chen, A. Buyuktosunoglu, A. Vega, Y. Kwark, L. Shan, D. Liu, J. Silbermann, B. Webb, R. Joshi, J. Knickerbocker, C. Tyberg</i>	
Author Index	